

# HVL192

## Silicon Epitaxial Planar Pin Diode for Wireless LAN

REJ03G0417-0100

Rev.1.00

Nov 24, 2005

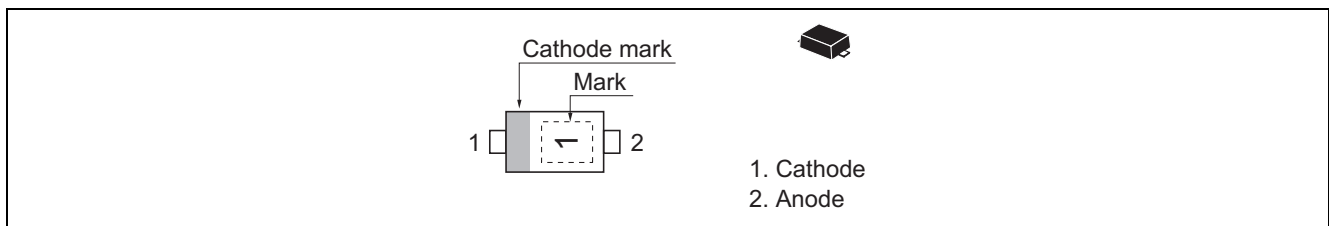
### Features

- Suitable for an antenna switches of wireless LAN and a cordless telephone.
- Super -Low capacitance.(C = 0.30 pF max)
- Low forward resistance. (rf = 3.2  $\Omega$  max)
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HVL192	1	EFP	PXSF0002ZA-A (EFP)

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	30	V
Forward current	$I_F$	50	mA
Power dissipation	$P_d$	100	mW
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	$I_R$	—	—	100	nA	$V_R = 30\text{ V}$
Forward voltage	$V_F$	—	—	1.0	V	$I_F = 10\text{ mA}$
Capacitance	C	—	—	0.30	pF	$V_R = 1\text{ V}, f = 1\text{ MHz}$
Forward resistance	$r_f$	—	—	3.2	$\Omega$	$I_F = 10\text{ mA}, f = 100\text{ MHz}$

Note: For EFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

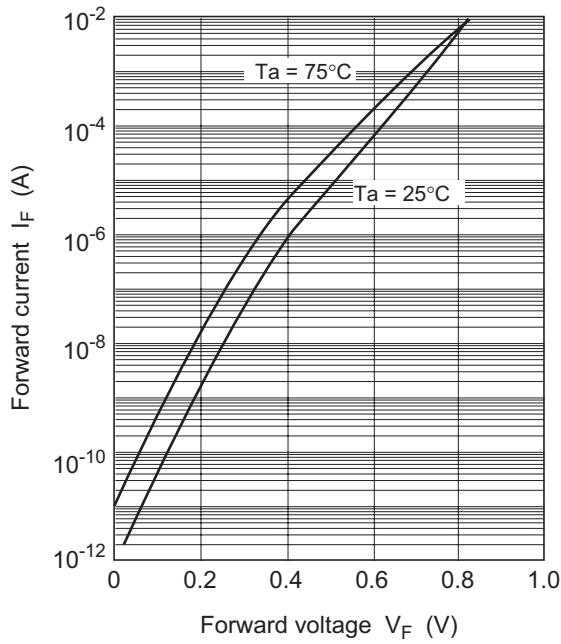


Fig.1 Forward current vs. Forward voltage

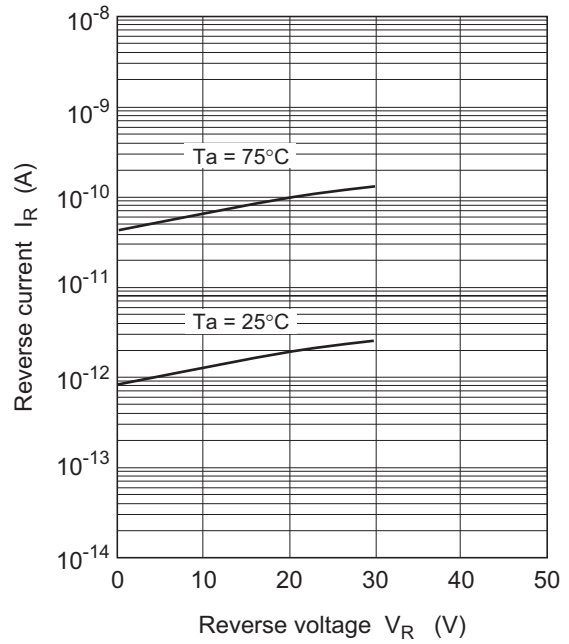


Fig.2 Reverse current vs. Reverse voltage

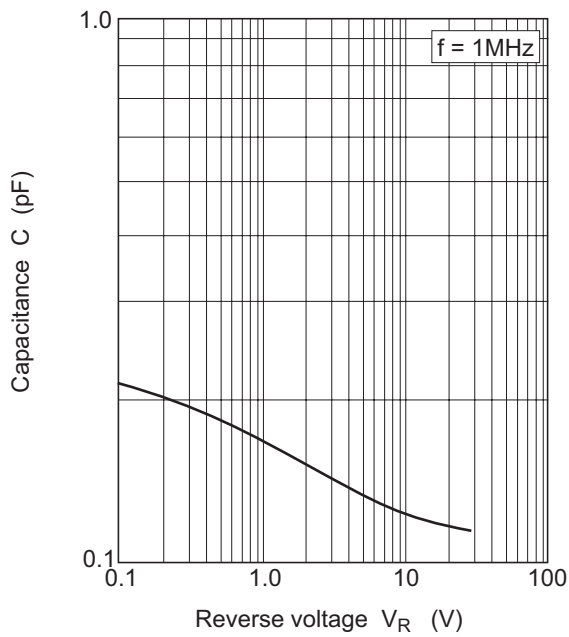


Fig.3 Capacitance vs. Reverse voltage

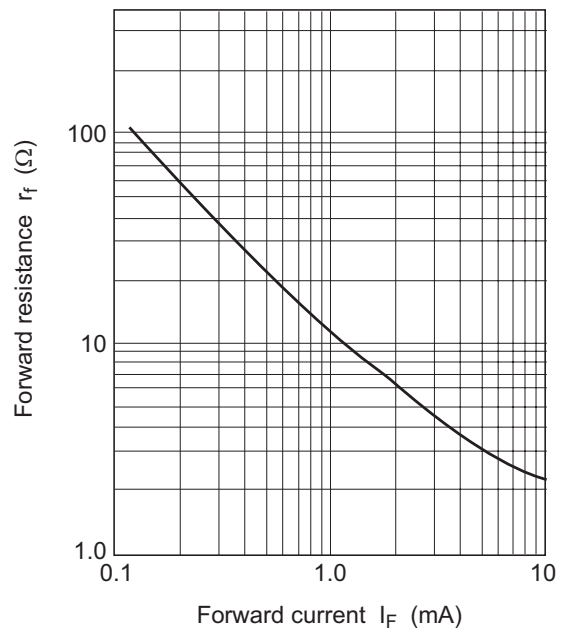
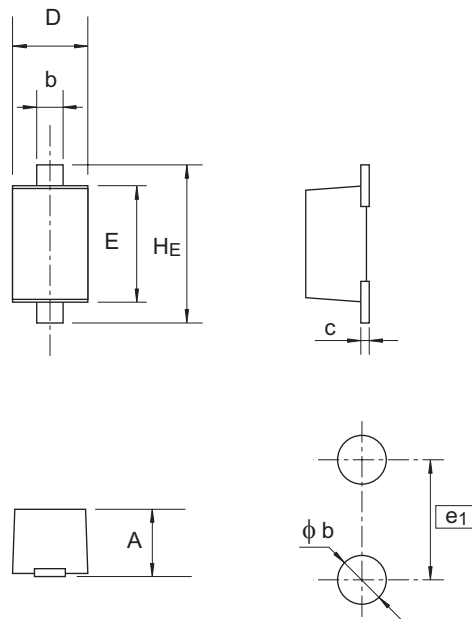


Fig.4 Forward resistance vs. Forward current

### Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
EFP	—	PXSF0002ZA-A	EFP / EFPV	0.0007g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.44	0.47	0.50
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.55	0.60	0.65
E	0.75	0.80	0.85
$H_E$	0.95	1.00	1.05
$\phi b$	—	0.40	—
$e_1$	—	1.00	—

**Keep safety first in your circuit designs!**

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